

ABSTRACT

A solder deposition method according to the present invention comprises the steps of: (1) providing a solder slab; (2) providing a complementary means having a plurality of through holes; (3)
5 providing a circuit element, which is composed of an insulating body and a plurality of embedded conducting terminals; (4) placing the circuit element under the complementary means and the solder slab above the complementary means, and injecting a plurality of solder bits taken from the solder slab by a punching
10 device through the complementary means into the solder-retaining units of the conducting terminals. This method is advantageous in the simplicity of soldering instrumentation and process, which significantly reduces production costs.